1658525-1 ✓ ACTIVE

AMPMODU

TE Internal #: 1658525-1

Wire-to-Board, 26 Position, 2.54 mm [.1 in] Centerline, Vertical, Through Hole - Solder, 2 Row, Plug, Ribbon Cable Connectors

View on TE.com >

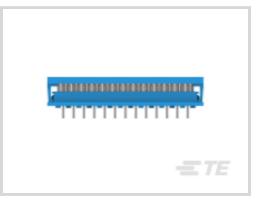


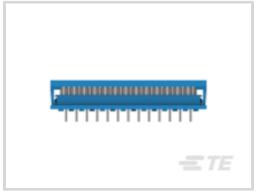
Connectors > PCB Connectors > Wire-to-Board Connectors > FFC, FPC & Ribbon Connectors > Ribbon Cable Connectors











Connector System: Wire-to-Board

Number of Positions: 26

Centerline (Pitch): 2.54 mm [.1 in]
PCB Mount Retention: Without
PCB Mount Orientation: Vertical

Features

Product Type Features

Ribbon Cable Connector Header Type	Shrouded
Connector Product Type	Connector Assembly
Connector System V	Wire-to-Board
Connector & Housing Type	Plug
Connector & Contact Terminates To	Printed Circuit Board, Wire & Cable

Configuration Features

Number of Positions	26
PCB Mount Orientation	Vertical
Number of Rows	2

Body Features

Contact Features

PCB Contact Termination Area Plating Material Thickness	2.54 μm[100 μin]
Contact Mating Area Plating Material	Tin (Sn)



Wire Contact Termination Area Plating Thickness	2.54 μm[100 μin]
PCB Contact Termination Area Plating Material	Tin
Wire Contact Termination Area Plating Material	Tin
Contact Current Rating (Max)	1 A
Termination Features	
Rectangular Termination Post & Tail Width	.46 mm[.018 in]
	.014 in
Termination Method to Wire & Cable	Insulation Displacement (IDC)
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
PCB Mount Retention	Without
Mating Retention	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
Usage Conditions	
Operating Temperature Range	-55 – 125 °C[-67 – 257 °F]

Product Compliance

Circuit Application

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.

Signal



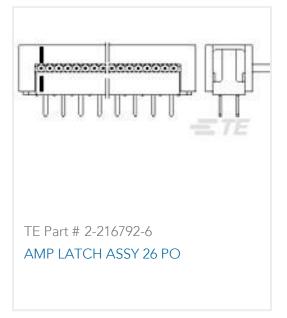
Solder Process Capability

Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

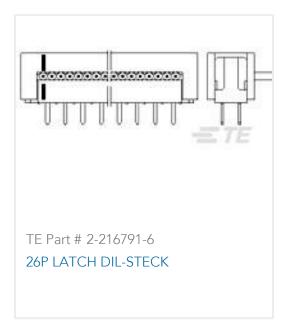
Compatible Parts











Customers Also Bought























Documents

Product Drawings

622-2653LF, PCB IDC, LEAD FREE

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1658525-1_B.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1658525-1_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1658525-1_B.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.